

What is claimed:

1. A nano-twin copper material with ultrahigh strength and high electrical conductivity was composed of roughly equiaxed submicron-sized grains, inside each grain, there are high density of growth-in twin lamellae with different orientations; and the twin lamellae with the same orientations are inter-parallel; The twin spacing ranges from several nanometers to 100 nm; and the lengths from 100-500 nm.
2. The nano-twin copper material with ultrahigh strength and high electrical conductivity according to the claim 1, characterized in that it has the following properties: density of  $8.93\pm0.03$  g/cm<sup>3</sup>, purity of  $99.997\pm0.02$  at%, yield strength of  $900\pm10$  MPa and elongation of  $13.5\pm0.5\%$  at room temperature at tensile strain rate of  $6\times10^{-3}$ /s, electrical resistivity at room temperature (293 K) of  $(1.75\pm0.02)\times10^{-8}$  Ω·m, the temperature coefficient of resistivity of  $6.78\times10^{-11}$  K<sup>-1</sup>.
3. The nano-twin copper material with ultrahigh strength and high electrical conductivity according to the claim 1, characterized in that the said submicron grain sizes range from 300-1000 nm.
4. A method for producing a nano-twin copper material with ultrahigh strength and high electrical conductivity according to the claim 1, characterized in that the electrodeposition technique is used, electron purity grade CuSO<sub>4</sub> solution is selected as electrolyte with the addition of ion-exchanged water or distilled water, pH of the said electrolyte is 0.5-1.5, anode is 99.99% pure Cu sheet and cathode is iron sheet or low carbon steel sheet with surface plated by Ni-P amorphous layer;

The said pulsed electrodeposition technique parameters comprise: pulse current density of 40~100 A/cm<sup>2</sup>; on-time ( $t_{on}$ ) of 0.01~0.05s and off-time ( $t_{off}$ ) of 1~3s; the distance between anode and cathode of 50~100mm, the area ratio of anode and cathode of (30~50):1; electrolyte temperature of 15~30°C; electrolyte in electromagnetic stirring;

Additive is a combination of 0.02-0.2 mL/L gelatine aqueous solution with concentration of 5-25% and 0.2-1.0 mL/L high-purity NaCl aqueous solution with concentration of 5-25%.